

IN THE CLAIMS

Claims 2-9 are pending in this application. Please cancel claims 1 and 18-19 without prejudice or disclaimer, and amend claims 2-9, as follows:

1. (Canceled)
2. (Currently Amended) A method of manufacturing a solid-state image sensing device ~~according to claim 1~~, comprising the steps of:
 - (a) preparing a wiring substrate mother board having a first face and a second face on the side opposite to said first face;
 - (b) mounting first electronic components over said first face of said wiring substrate mother board;
 - (c) encapsulating said first electronic components by using an encapsulation body;
 - (d) mounting second electronic components including image sensors over said second face of said wiring substrate mother board; and
 - (e) joining a frame to said second face of said wiring substrate mother board so as to cover said second electronic components,
 - wherein said frame has a position adjustment pin for adjusting the position of said frame with said wiring substrate mother board,
 - wherein said wiring substrate mother board has a through hole into which said position adjustment pin is to be inserted, and
 - wherein said position adjustment pin and said through hole are provided outside a junction face between said frame and said wiring substrate mother board,
 - wherein said step (e) includes a sub-step of selectively coating a junction face of said frame with a bonding agent through a mask, and said sub-step of selectively coating a junction face of said frame with a bonding agent is carried out in such a way that said position adjustment pin of said frame is not coated with said bonding agent.
3. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim ~~[[1]]~~2, wherein in said step (c), said encapsulation body is formed in such a way that said through hole of said wiring substrate mother board is avoided.

4. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim ~~[[1]]~~2,
wherein said wiring substrate mother board has a plurality of module regions,
wherein said encapsulation body used in said step (c) is a batch encapsulation body for encapsulating said first electronic components in said module regions in the aggregate, and
wherein in said step (c), said batch encapsulation body is formed in such a way that said through hole of said wiring substrate mother board is avoided.
5. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim 4, wherein in said step (c), a plurality of said batch encapsulation bodies is formed over said first face of said wiring substrate mother board with said batch encapsulation bodies being separated from each other.
6. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim 5, wherein a depression is formed in a portion of each of said batch encapsulation bodies.
7. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim 4, wherein in said step (c), said module regions are divided into a plurality of groups and a plurality of said first electronic components in each of said groups is encapsulated in the aggregate.
8. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim 7, wherein in said step (c), an encapsulation material is supplied to any particular one of said groups through an encapsulation-material-supplying path provided for said particular one of said groups so as to form said encapsulated body for said particular one of said groups in the aggregate.
9. (Currently Amended) ~~[[A]]~~The method of manufacturing a solid-state image sensing device according to claim ~~[[1]]~~2, wherein said image sensors are each a CMOS image sensor.

10. (Withdrawn) A method of manufacturing a solid-state image sensing device comprising the steps of:
- (a) preparing a wiring substrate mother board having a first face and a second face on the side opposite to said first face;
 - (b) mounting first electronic components over said first face of said wiring substrate mother board;
 - (c) encapsulating said first electronic components by using an encapsulation body;
 - (d) mounting second electronic components including image sensors over said second face of said wiring substrate mother board; and
 - (e) joining a frame to said second face of said wiring substrate mother board so as to cover said second electronic components,
- wherein said frame has a position adjustment pin for adjusting the position of said frame with respect to said wiring substrate mother board,
- wherein said wiring substrate mother board has a through hole into which said position adjustment pin is to be inserted, and
- wherein in said step (c), said encapsulation body is formed in such a way that said through hole is avoided.
11. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 10,
- wherein said wiring substrate mother board has a plurality of module regions, and said step (c) is a step of forming said encapsulation body as a batch encapsulation body for encapsulating said first electronic components in said module regions in the aggregate.
12. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 11, wherein a plurality of said batch encapsulation bodies is formed over said first face of said wiring substrate parent substrate with said batch encapsulation bodies being separated from each other.
13. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 12, wherein a depression is formed in a portion of each of said batch encapsulation bodies.

14. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 11, wherein in said step (c), said module regions are divided into a plurality of groups and a plurality of said first electronic components in each of said groups is encapsulated in the aggregate.
15. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 14, wherein in said step (c), an encapsulation material is supplied to any particular one of said groups through an encapsulation-material-supplying path provided for said particular one of said groups so as to form said encapsulated body for said particular one of said groups in the aggregate.
16. (Withdrawn) A method of manufacturing a solid-state image sensing device comprising the steps of:
- (a) preparing a wiring substrate mother board having a first face and a second face on the side opposite to said first face;
 - (b) mounting first electronic components over said first face of said wiring substrate mother board;
 - (c) encapsulating said first electronic components by using an encapsulation body;
 - (d) mounting second electronic components including image sensors over said second face of said wiring substrate mother board;
 - (e) joining a frame to said second face of said wiring substrate mother board so as to cover said second electronic components;
 - (f) cutting out individual module regions from said wiring substrate mother board obtained as a result of said step (e); and
 - (g) mounting a lens holder housing optical lens to said frame in each of said individual module regions obtained as a result of said step (f),
- wherein said wiring substrate mother board has a plurality of said module regions,
- wherein said frame has a position adjustment pin for adjusting the position of said frame with respect to said wiring substrate mother board,
- said wiring substrate mother board has a through hole into which said position adjustment pin is to be inserted;
- wherein said position adjustment pin and said through hole are provided outside a junction face between said frame and said wiring substrate mother board,

wherein said encapsulation body used in said step (c) is a batch encapsulation body for encapsulating said first electronic components in said module regions in the aggregate, and

wherein a plurality of said batch encapsulation bodies is formed over said wiring substrate mother board with said batch encapsulation bodies separated from each other to avoid said through hole.

17. (Withdrawn) A method of manufacturing a solid-state image sensing device according to claim 16, wherein said image sensors are each a CMOS image sensor.

18-19. (Canceled)